Assembly Bill of Materials PMP9457

Texas Instruments

| Designator | Quantity | PartNumber | Manufacturer | Value | PackageReference | Description |
|--------------------------------|----------|---------------------|---------------------|---------|-------------------------------|---|
| BIAS, EN, PG, PG_PULL_UP, SYNC | 5 | 5014 | Keystone | Yellow | Yellow Multipurpose Testpoint | Test Point, Multipurpose, Yellow, TH |
| C04, C05 | 2 | 08051C223JAT2A | AVX | 0.022uF | 0805 | CAP, CERM, 0.022uF, 100V, +/-5%, X7R, 0805 |
| CBIAS | 1 | C2012X5R1H475K125AB | TDK | 4.7uF | 0805 | CAP, CERM, 4.7uF, 50V, +/-10%, X5R, 0805 |
| CBOOT | 1 | 0805YC474KAT2A | AVX | 0.47uF | 0805 | CAP, CERM, 0.47uF, 16V, +/-10%, X7R, 0805 |
| CIN3 | 3 | C5750X7S2A106M | TDK | 10uF | 2220 | CAP, CERM, 10uF, 100V, +/-20%, X7S, 2220 |
| CF1 | 1 | GCM32ER71H475KA5L | MuRata | 4.7uF | 1210 | Multilayer Ceramic Capacitors MLCC - SMD/SMT 1210 4.7uF 50volts X7R 10% |
| CFF | 1 | GRM1885C1H101JA01D | MuRata | 100pF | 0603 | CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603 |
| CFF1 | 3 | C0805C104K1RACTU | Kemet | 0.1uF | 0805 | CAP, CERM, 0.1uF, 100V, +/-10%, X7R, 0805 |
| CIN1 | 1 | GRM21BR72A474KA73L | MuRata | 0.47uF | 0805 | CAP, CERM, 0.47uF, 100V, +/-10%, X7R, 0805 |
| CIN2 | 1 | GRM32ER72A105KA01L | MuRata | 1uF | 1210 | CAP, CERM, 1uF, 100V, +/-10%, X7R, 1210 |
| CIN4 | 1 | EEV-FK2A680Q | Panasonic | 68uF | SMT Radial H13 | CAP, AL, 68uF, 100V, +/-20%, 0.32 ohm, SMD |
| CO1, CO2 | 2 | GRM32ER71A476KE15L | MuRata | 47uF | 1210 | CAP, CERM, 47uF, 10V, +/-10%, X7R, 1210 |
| CO3 | 1 | 08053D105KAT2A | AVX | 1uF | 0805 | CAP, CERM, 1uF, 25V, +/-10%, X5R, 0805 |
| CSS | 1 | C1608X7R1H473K | ТDК | 0.047uF | 0603 | CAP, CERM, 0.047uF, 50V, +/-10%, X7R, 0603 |
| CVCC1 | 1 | GRM188R71A225KE15D | MuRata | 2.2uF | 0603 | CAP, CERM, 2.2uF, 10V, +/-10%, X7R, 0603 |
| CVCC2 | 1 | C3216X7R1A106M | ТDК | 10uF | 1206 | CAP, CERM, 10uF, 10V, +/-20%, X7R, 1206 |
| GND | 3 | 5011 | Keystone | Black | Black Multipurpose Testpoint | Test Point, Multipurpose, Black, TH |
| J1 | 1 | TSW-102-07-G-S | Samtec | | 2x1 Header | Header, TH, 100mil, 2x1, Gold plated, 230 mil above insulator |
| J2, J3 | 2 | ED120/2DS | On-Shore Technology | | TERM_BLK, 2pos, 5.08mm | TERMINAL BLOCK 5.08MM VERT 2POS, TH |
| LF1 | 2 | MPI4040R2-2R2-R | Coiltronics | 2.2uH | IND_4.5x1.5x4.1mm | Inductor, Shielded, ?, 2.2uH, 1.5A, 0.082 ohm, SMD |
| L_60V_HC | 1 | DR125-100-R | Coiltronics | 10uH | DR125 | Inductor, Shielded Drum Core, Ferrite, 10uH, 5.35A, 0.0189 ohm, SMD |
| RBIAS | 1 | CRCW06030000Z0EA | Vishay-Dale | 0 | 0603 | RES, 0 ohm, 5%, 0.1W, 0603 |
| RENB, RFBT | 2 | CRCW06031M00FKEA | Vishay-Dale | 1.00Meg | 0603 | RES, 1.00Meg ohm, 1%, 0.1W, 0603 |
| RENT, RFBB1 | 2 | CRCW0603590KFKEA | Vishay-Dale | 590k | 0603 | RES, 590k ohm, 1%, 0.1W, 0603 |
| RFBB | 1 | CRCW0603432KFKEA | Vishay-Dale | 432k | 0603 | RES, 432k ohm, 1%, 0.1W, 0603 |
| RPG1, RPG2, RSYNC | 3 | CRCW0603100KFKEA | Vishay-Dale | 100k | 0603 | RES, 100k ohm, 1%, 0.1W, 0603 |
| RT | 1 | CRCW060382K5FKEA | Vishay-Dale | 82.5k | 0603 | RES, 82.5k ohm, 1%, 0.1W, 0603 |
| SH-J1 | 1 | 969102-0000-DA | 3M | 1x2 | Shunt | Shunt, 100mil, Gold plated, Black |
| SW | 1 | 5012 | Keystone | White | White Multipurpose Testpoint | Test Point, Multipurpose, White, TH |
| TC1 | 1 | PTS080501B100RP100 | Vishay/Beyschlag | 100ohm | 0805 | Temperature Sensor, 100ohm, 1%, TC=+3850ppm, 0805, SMT |
| U1 | 1 | LM46002PWP | Texas Instruments | | PWP0016F | 3.5 - 36V 3A Step-Down Converters with Low Quiescent Current, PWP0016F |
| VIN | 1 | 5010 | Keystone | Red | Red Multipurpose Testpoint | Test Point, Multipurpose, Red, TH |
| VOUT | 1 | 5013 | Keystone | Orange | Orange Multipurpose Testpoint | Test Point, Multipurpose, Orange, TH |

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